



# CERTIFICATE



This is to certify that

## Unimicron Technology Corp. (IC Carrier SBU)

Plant S1, S2, S3  
No. 179, Shanying Road, Guishan District  
Taoyuan City 333  
Taiwan (R.O.C.)

with the organizational units/sites as listed in the annex

has implemented and maintains a **Quality Management System**.

Scope:

The manufacture of IC carriers including substrates for Ball Grid Array (BGA), Land Grid Array (LGA) and Flip Chip Package.

Through an audit, documented in a report, it was verified that the management system fulfills the requirements of the following standard:

## ISO 9001 : 2015

Certificate registration no.	20003411 QM15
Date of revision	2022-06-24
Date of certification	2021-06-16
Valid until	2024-06-15



**DQS Inc.**

Brad McGuire  
Managing Director

Accredited Body: DQS Inc., 1500 McConnor Parkway, Suite 400, Schaumburg, IL 60173 USA  
Administrative Office: DQS Taiwan Inc., 8F, 23, Yuan Huan West Road, Feng Yuan Dist.,  
Taichung City, Taiwan 420





**Annex to certificate**  
**Registration No. 20003411 QM15**

**Unimicron Technology Corp. (IC Carrier SBU)**

Plant S1, S2, S3  
No. 179, Shanying Road, Guishan District  
Taoyuan City 333  
Taiwan (R.O.C.)

**Location**

**Scope**

**20005494**  
**Unimicron Technology Corp.**  
**(IC Carrier SBU)**  
Plant H1, H3  
No. 290, Zhonglun Village  
Xinfeng Township, Hsinchu 304  
Taiwan (R.O.C.)

The manufacture of IC carriers including substrates for Ball Grid Array (BGA), Land Grid Array (LGA) and Flip Chip Package.

**50600474**  
**Unimicron Technology Corp.**  
**(IC Carrier SBU)**  
No. 68, Ln. 426, Sec. 1, Meishi Rd.  
Yangmei Dist., Taoyuan City 326015  
Taiwan (R.O.C.)

The manufacture of IC carriers including substrates for Ball Grid Array (BGA), Land Grid Array (LGA) and Flip Chip Package.